US00D877706S

(12) **United States Design Patent**
Karasawa

(10) **Patent No.: US D877,706 S**
(45) **Date of Patent: ** Mar. 10, 2020**

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(54) **CASSETTE DISPLACEMENT PREVENTION JIG OF SEMICONDUCTOR MANUFACTURING APPARATUS**

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(**) Term: **15 Years**

(21) Appl. No.: **29/610,851**

(22) Filed: **Jul. 17, 2017**

(30) **Foreign Application Priority Data**

Jan. 18, 2017 (JP) 2017-000728

(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC .... D13/182, 184, 199; D15/144, 144.1, D15/199, 140; 204/297.08; 414/935–940; 269/903, 126, 71, 58; 248/694; 451/364; 427/457, 533; 118/723 E; 438/485; 156/345.44
CPC . H01L 21/673; H01L 21/67; H01L 21/67326; B24B 41/06; B23P 1/02
See application file for complete search history.

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(57) **CLAIM**

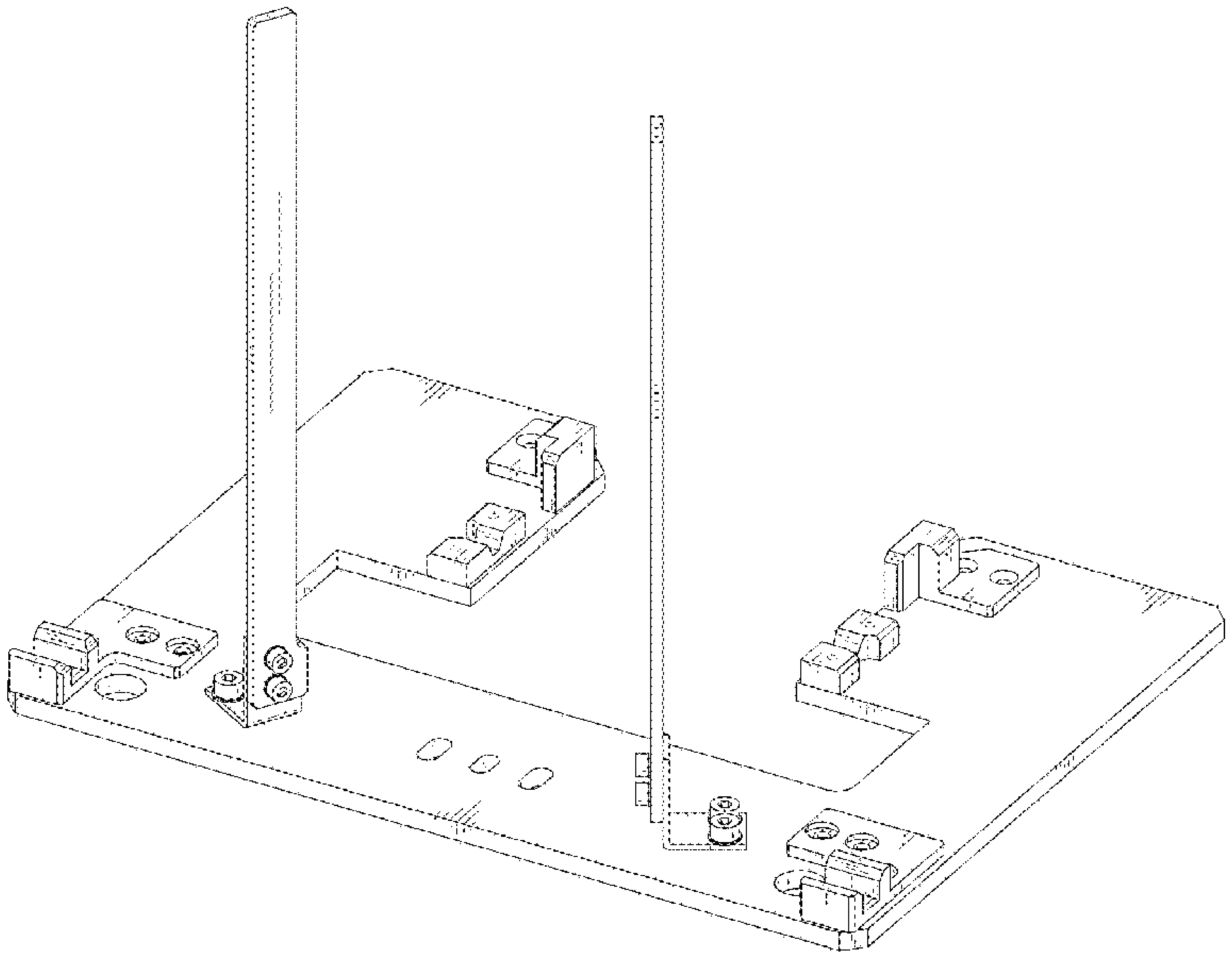
The ornamental design for a cassette displacement prevention jig of semiconductor manufacturing apparatus, as shown and described.

DESCRIPTION

FIG. **1** is a front, top and right side perspective view of a cassette displacement prevention jig of semiconductor manufacturing apparatus showing my new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a right side elevational view thereof;
FIG. **5** is a left side elevational view thereof;
FIG. **6** is a top plan view thereof;
FIG. **7** is a bottom plan view; and,
FIG. **8** is a cross-sectional view taken along line **8-8** in FIG. **2**.

The broken lines in FIG. **1**, FIG. **6** and FIG. **7** are intended to illustrate the portions that do not form the claimed design.

1 Claim, 8 Drawing Sheets



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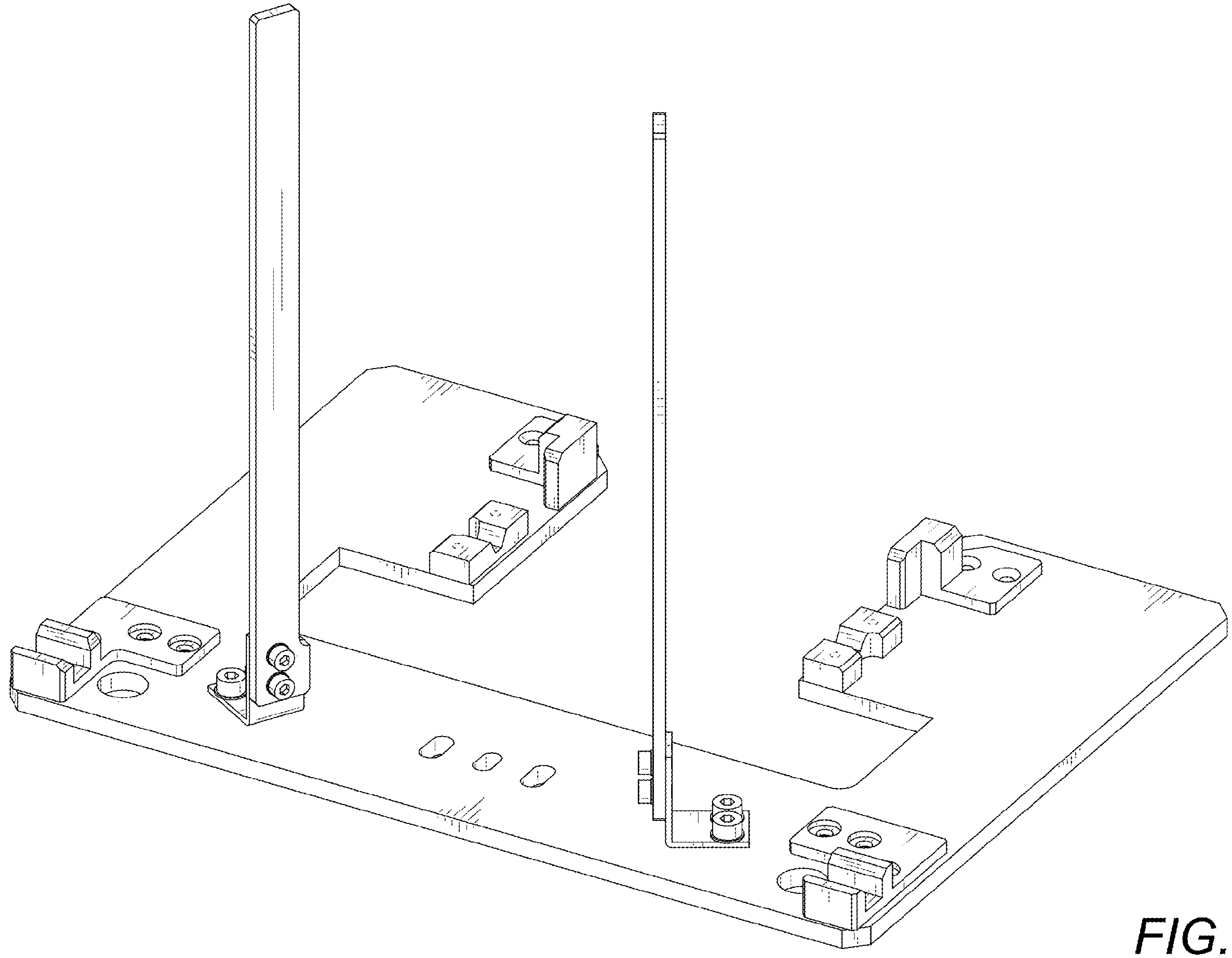

FIG. 1

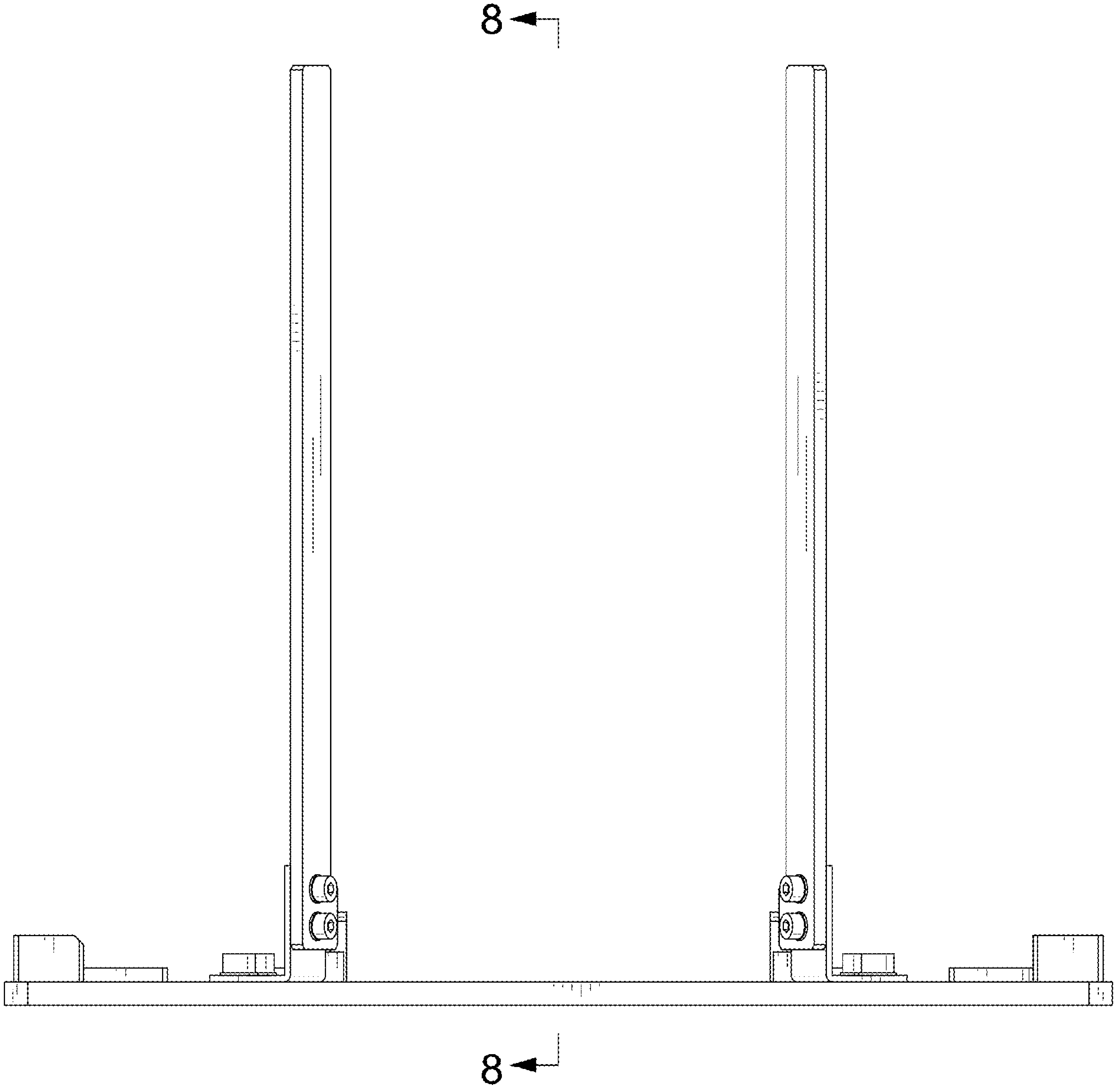

FIG. 2

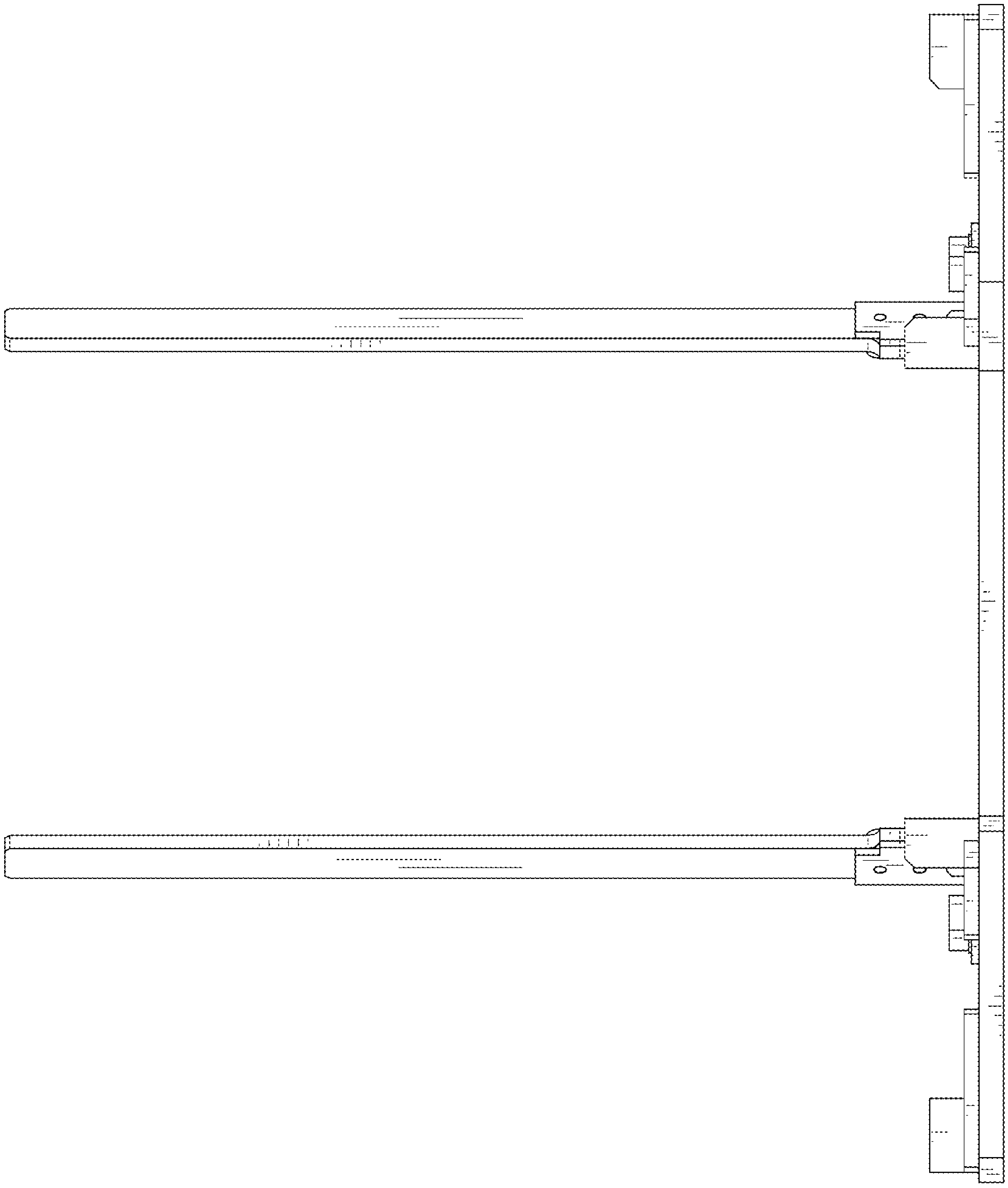

FIG. 3

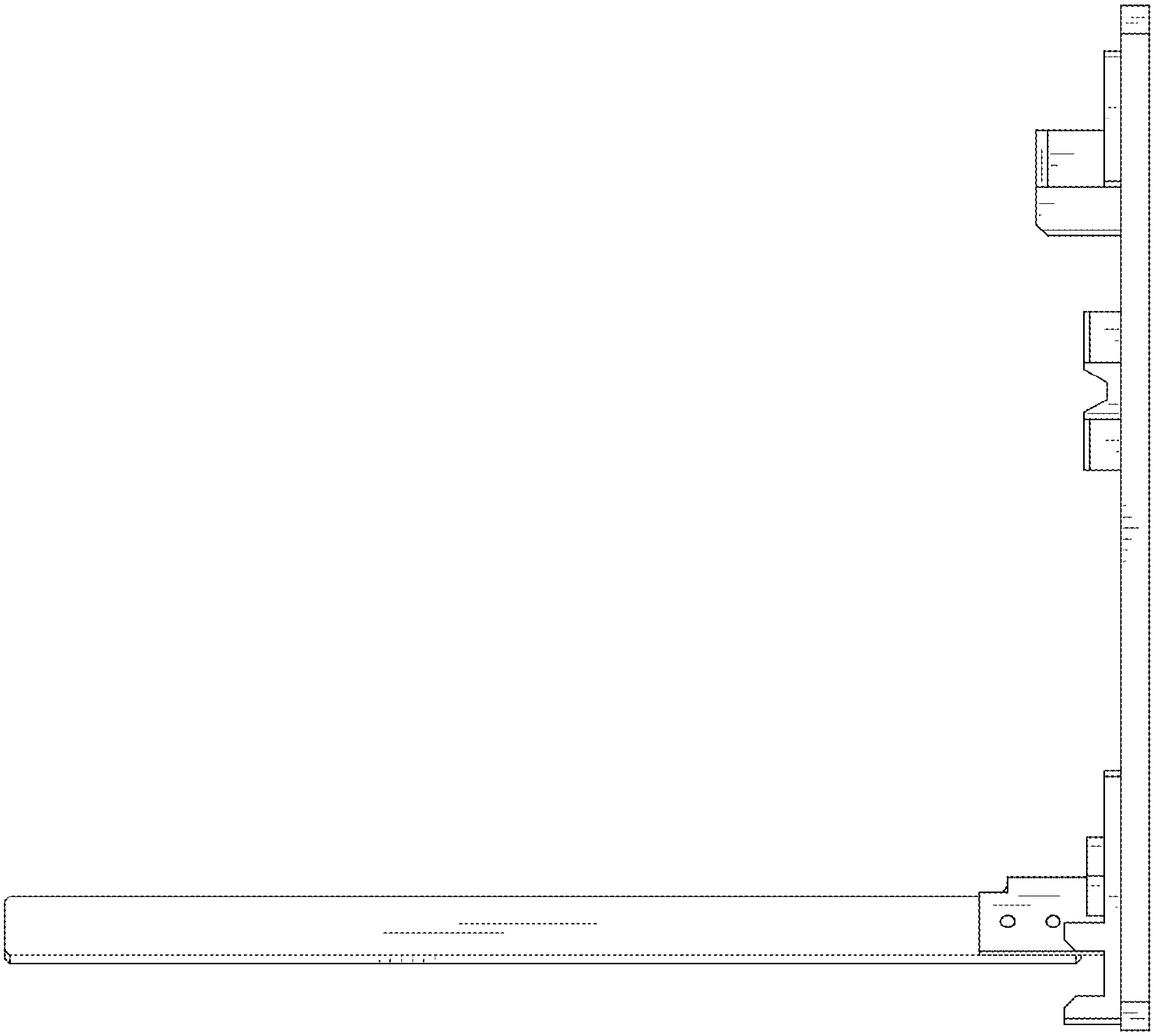

FIG. 4

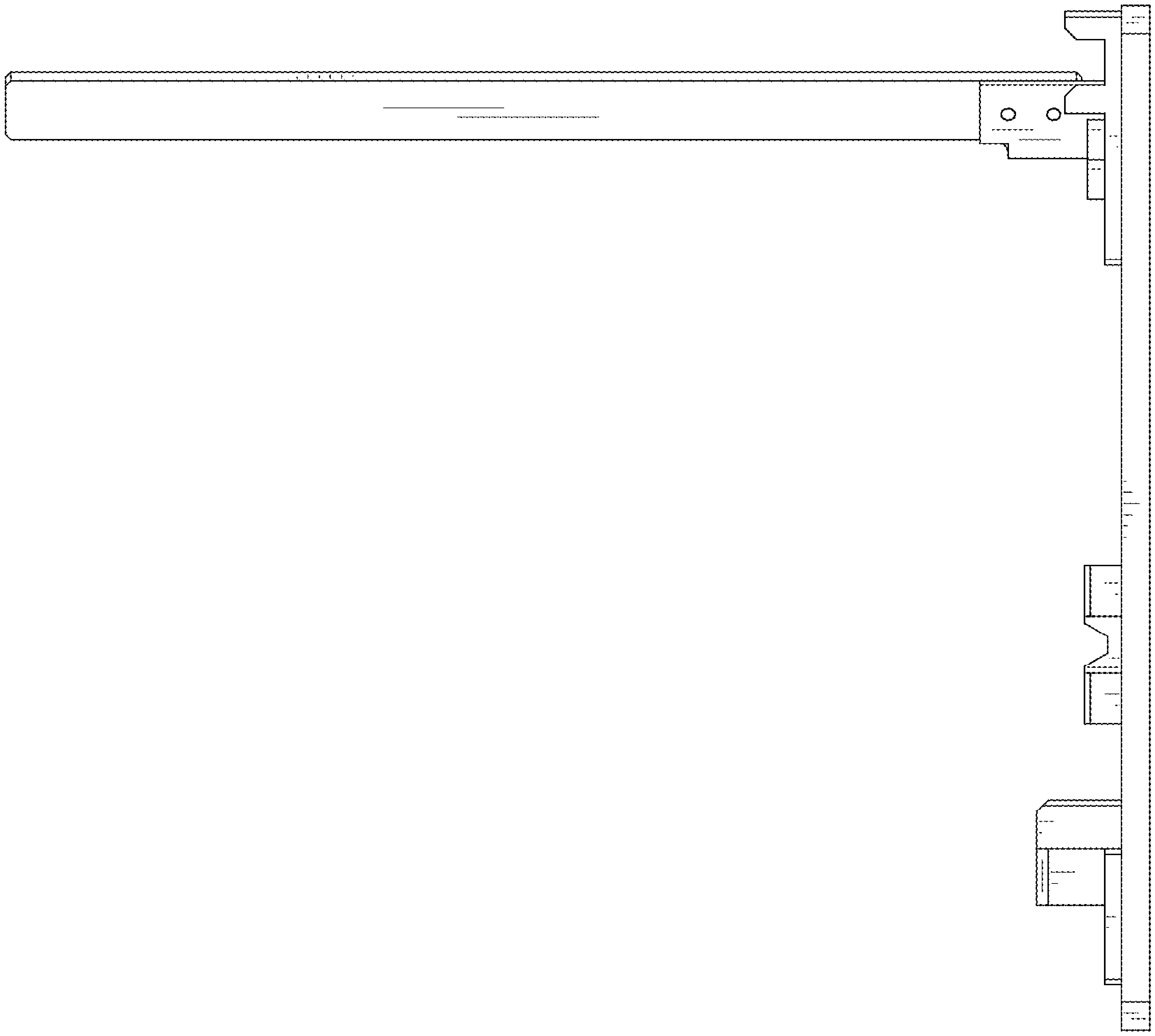

FIG. 5

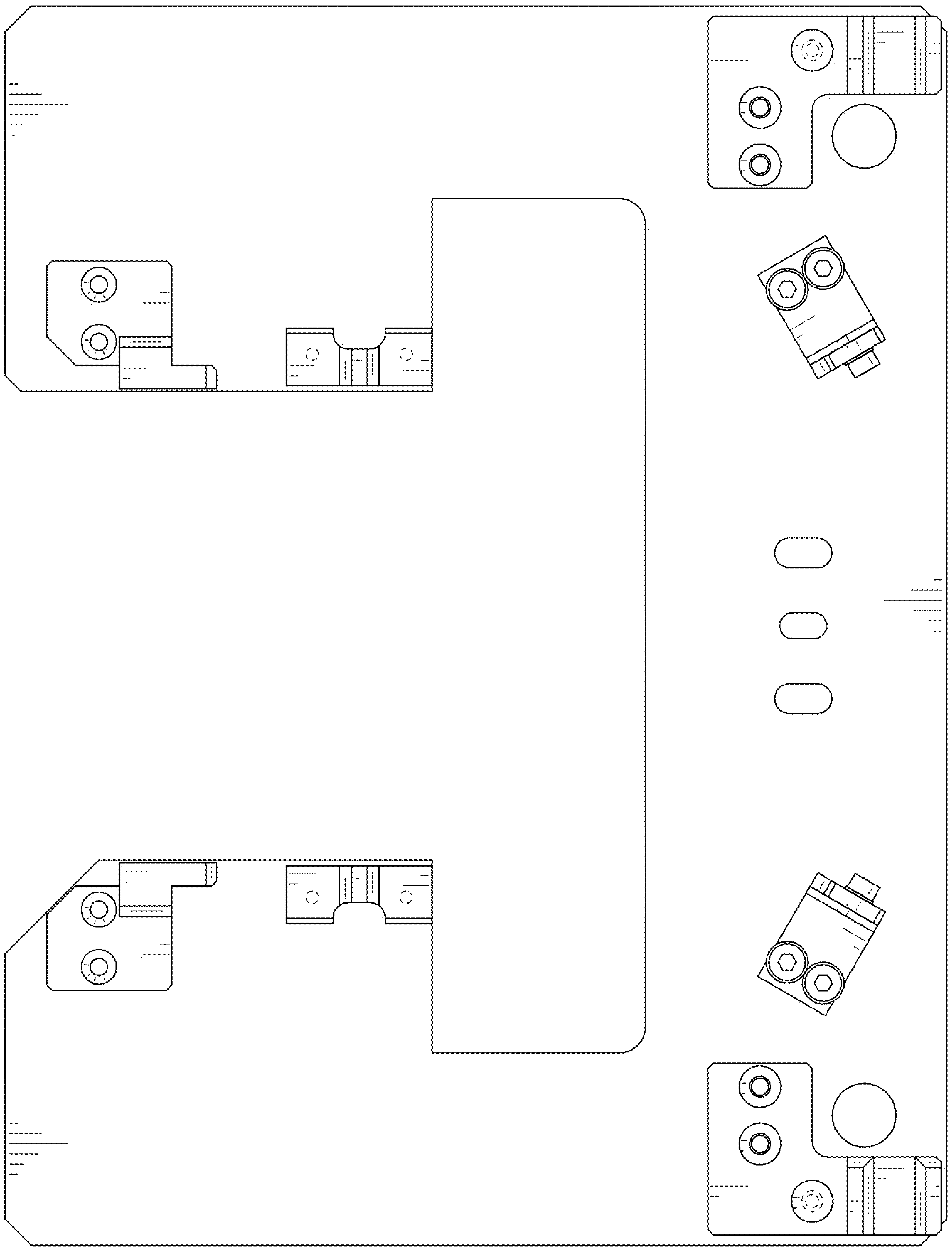

FIG. 6

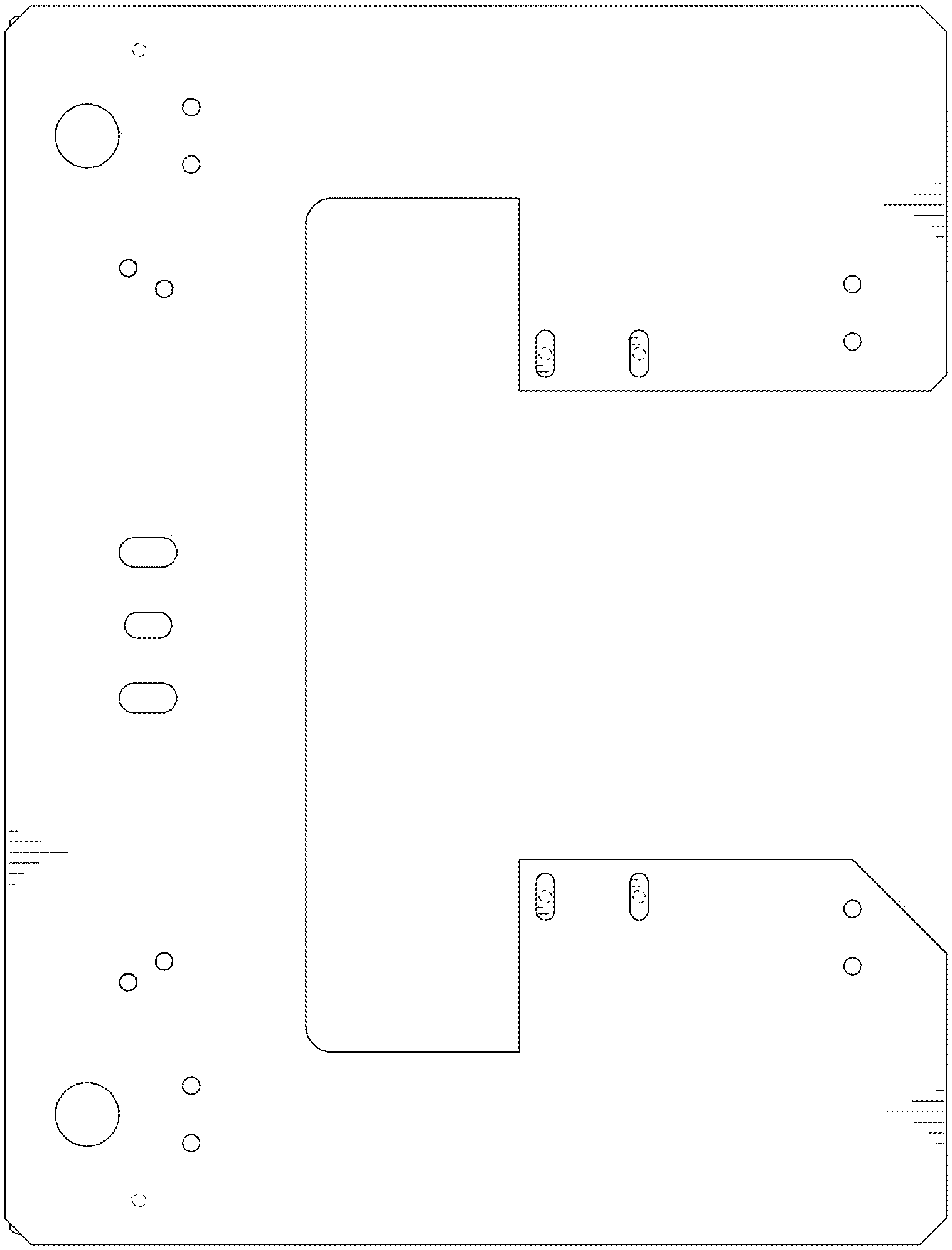

FIG. 7

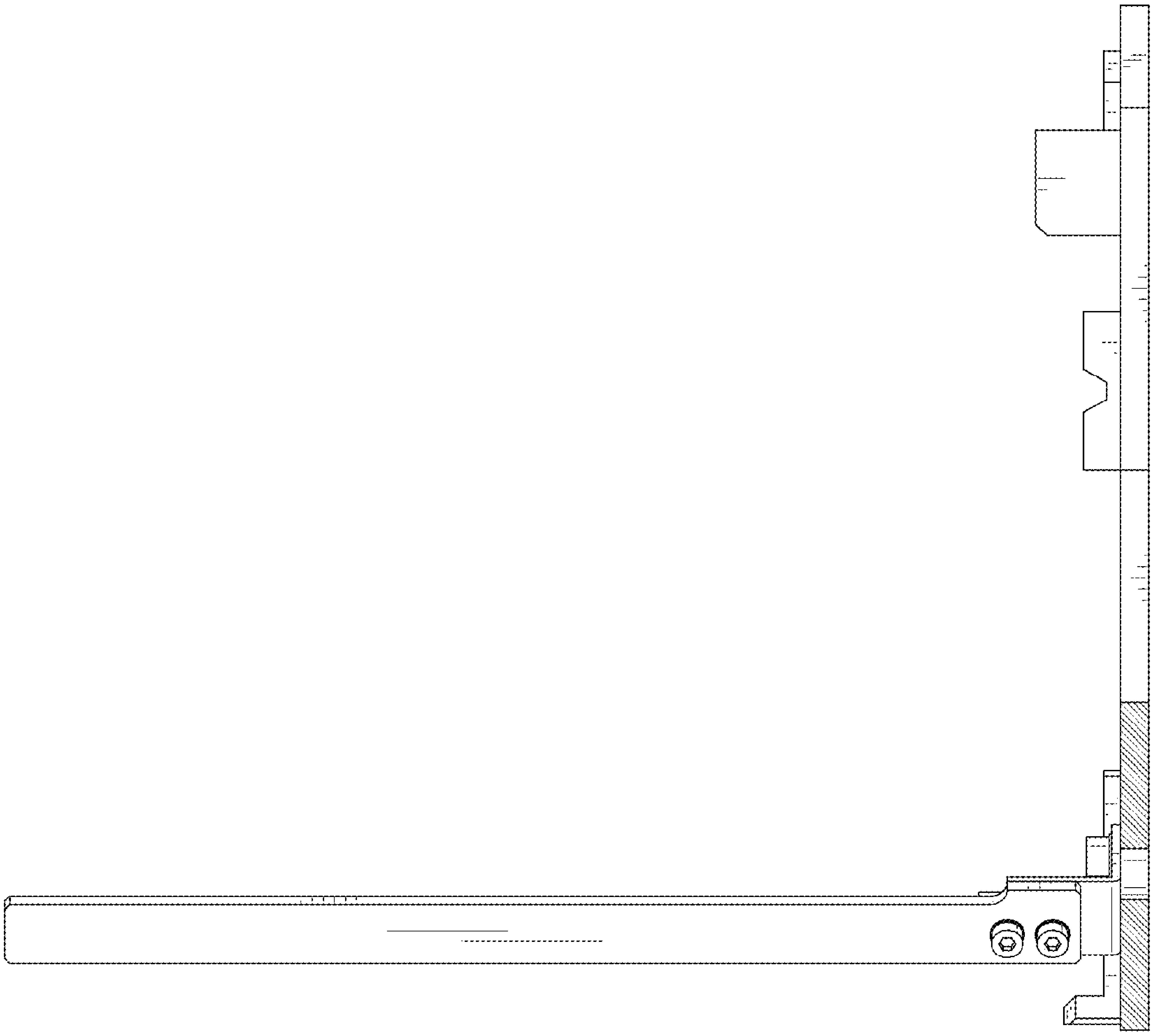

FIG. 8